

L Number	Hits	Search Text	DB	Time stamp
1	165631	(stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 08:38
2	512643	(heat with (spreader sink metal slug radiate cooling))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 08:59
3	7618	((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling)))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 08:44
4	1501	((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling))) and (thermal with expansion)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:00
5	987	(epoxy molding encapsulate encapsulation encapsulated) and (((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling))) and (thermal with expansion))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:02
6	941	(substrate carrier board) and ((epoxy molding encapsulate encapsulation encapsulated) and (((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling))) and (thermal with expansion)))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:02
7	544878	(heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:00
8	60483	((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:01
9	5722	((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:01
10	5142	(substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))))	USPAT; US-PPGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:02

11	3450	(epoxy molding encapsulate encapsulation encapsulated) and ((substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:02
12	2837	((epoxy molding encapsulate encapsulation encapsulated) and ((substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))))) and (package packaged packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:04
13	2009	((epoxy molding encapsulate encapsulation encapsulated) and ((substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))))) and (package packaged packaging)) not ((substrate carrier board) and ((epoxy molding encapsulate encapsulation encapsulated) and (((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))) same ((heat with (spreader sink metal slug radiate cooling)))) and (thermal with expansion))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:06

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1	165631	(stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 08:38
2	512643	(heat with (spreader sink metal slug radiate cooling))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 08:59
3	7618	((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 08:44
4	1501	((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling))) and (thermal with expansion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:00
5	987	(epoxy molding encapsulate encapsulation encapsulated) and (((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling))) and (thermal with expansion))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:02
6	941	(substrate carrier board) and ((epoxy molding encapsulate encapsulation encapsulated) and (((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling))) and (thermal with expansion)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:02
7	544878	(heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:25
8	60483	((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:01
9	5722	((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:01
10	5142	(substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:02

11	3450	((epoxy molding encapsulate encapsulation encapsulated) and ((substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:02
12	2837	((epoxy molding encapsulate encapsulation encapsulated) and ((substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))))) and (package packaged packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:04
13	2009	((epoxy molding encapsulate encapsulation encapsulated) and ((substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))))) and (package packaged packaging)) not ((substrate carrier board) and ((epoxy molding encapsulate encapsulation encapsulated) and (((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))) and (package packaged packaging)) not ((substrate carrier board) and ((epoxy molding encapsulate encapsulation encapsulated) and (((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))) same ((heat with (spreader sink metal slug radiate cooling))) and (thermal with expansion))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:06
14	467	((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) and ((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and 257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:24
15	2469	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:24
16	2222	257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:24
17	3741	257/686 257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:24
18	786	((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) and ((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (257/686 257/777)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:25

19	621	((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) and ((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (257/686 257/777)) not (((epoxy molding encapsulate encapsulation encapsulated) and ((substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))))) and (package packaged packaging)) not ((substrate carrier board) and ((epoxy molding encapsulate encapsulation encapsulated) and (((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))) and ((heat with (spreader sink metal slug radiate cooling))) and (thermal with expansion)))).	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:25
20	621	((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling)) and (((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) and ((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (257/686 257/777)) not (((epoxy molding encapsulate encapsulation encapsulated) and ((substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))))) and (package packaged packaging)) not ((substrate carrier board) and ((epoxy molding encapsulate encapsulation encapsulated) and (((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))) same ((heat with (spreader sink metal slug radiate cooling))) and (thermal with expansion))))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:26